

## **3EQHM572R Low EMI Oscillator**

# 7 x 5 x 1.4mm SMD - Specification Group 'R'

Page 1 of 2

- Provides up to -12dB reduction in system EMI
- 'Drop-in' replacement for standard clocks
- Choice of modulation rate and spread
- Miniature package: 7.0 mm x 5.0 mm x 1.4mm

In electrical systems the principal cause of electromagnetic interference (EMI) is the system clock oscillator. Traditional methods of 'patching-up' systems with too high a level of EMI is to use ferrite beads, filters, ground planes, metal shielding and similar costly methods, However, the most efficient and economic method to reduce EMI is to reduce it at source: replace the system clock ocillator with a low EMI clock oscillator.

Compared with conventional clock oscillators, Spread Spectrum (Dithered) Oscillators can reduce EMI by as much as 15dB. The part is a 'drop-in' replacement for a standard clock oscillator hence there is no requirement to re-design existing PCBs.

### **APPLICATIONS**

- Printers, Multiple Function Printers (MPCs)
- Digital Copiers; PDAs
- Networking: LAN/WAN; Routers
- Storage Systems (CD-ROM, VCD, DVD, HDD)
- Scanners; Modems; Projectors
- Embedded Systems
- Musical Instruments
- Automotive: GPS car navigation systems
- LCD PC Monitors; LSD TVs
- ADSL; PCMCIA
- Still Digital Cameras (SDCs)

### **DESCRIPTION**

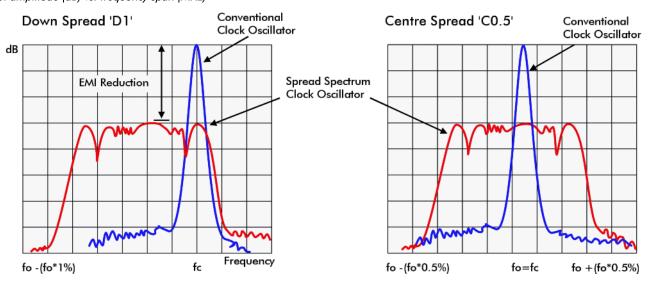
EQHM572 series low EMI oscillators can reduce system EMI by -12dB. The oscillators are a 'drop-in' replacement for standard oscillators. EMI reduction is achieved by the use of Spread Spectrum Technology whereby the mode energy is spread over a wider bandwidth. The modulation carrier frequency, operating in the kHz region, makes the process transparent to the oscillator frequency. There is a choice of modulation rates and spread to suit application requirements.

### SPREAD SPECTRUM TECHNOLOGY

Unlike a conventional clock oscillator, in a Spread Spectrum Clock Oscillator the mode energy is spread over a wider bandwidth. This is achieved by the frequency modulation technique. The controlled modulation process may be applied to the 'down' side of the nominal frequency (known as **DOWN SPREAD**,) or spread equally either side of nominal (**CENTRE SPREAD**). Down Spread is preferred if overclocking would cause a problem to the system.

### **MODULATION TYPES - EXAMPLES**

Output amplitude (dB) vs. frequency span (MHz)





## **3EQHM572R Low EMI Oscillator**

# 7 x 5 x 1.4mm SMD - Group 'R'

## 6.0MHz to 160MHz

### **SPECIFICATION**

Model No: 3EQHM572 (Group 'R')
Frequency Range: 3.5MHz to 165.0MHz
Spread Types: See table below

EMI Reduction\*: -7dBc min. 100MHz at C0.25\*\*

-9dBc min. 100MHz at C0.5\*\*
-15dBc min. 100MHz at C1.5\*\*
With reference to dB level at no

modulation.

Modulation Carrier Frequency: 6.9kHz min, 55.5kHz max.

Frequency dependent Call for details

Output Logic: CMOS

Input Voltage:  $Vdd = +3.3VDC \pm 5\%$ 

Frequency Stability\*\*\*

Commercial (0~70°C):  $\pm 25$ ppm (Spec. code = 'A')  $\pm 50$ ppm (Spec. code = 'B')  $\pm 100$ ppm (Spec. code = 'C')

Industrial (-40 $\sim$ +85 $^{\circ}$ C):

±25ppm (Spec. code = 'D') ±50ppm (Spec. code = 'E') ±100ppm (Spec. code = 'F') 2.0V min., 3.2V typ. (90%Vdd)

Output Voltage HIGH '1': 2.0V min., 3.2V typ. (90%Vdd)
Output Voltage LOW '0': 0.8V max., 0.2V typ. (10%Vdd)
Rise/fall Times: 4ns max, (frequency dependant)

Load: 15pF

Start-up Time: 2ms typical, 5ms max. Storage Temperature: -65° to +150°C

Current Consumption:

 10 ~ 50MHz:
 10mA typical

 50 ~ 125MHz:
 18mA typical

Duty Cycle: 50%±5% (CL=15pF, 50%Vdd)
Cyle to Cycle Jitter: ±250ps typ. ±300ps max.

Output Impedance: 40 Ohms typical

Static Discharge Voltage: >2000V (per MIL STD 833)
Ageing: ±5ppm /year max at Ta=25°C
Packaging: EIA 16mm tape and reel, 1k per.
Pad 1 Option: Output Enable/Disable. Output is

high impedance when taken low Output enable time 100ns max.

### Notes:

\* EMI reduction is applied to the entire frequency spectrum

\*\* dBc: with respect to no modulation. Frequency and total % spread dependant.

\*\*\* Frequency Stability parameter excludes modulation.

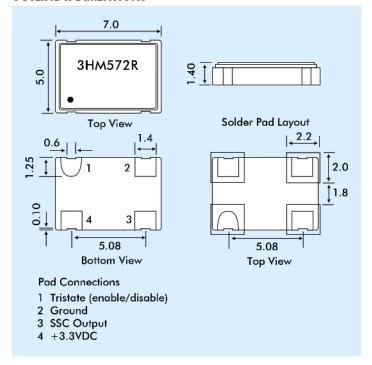






Page 2 of 2

### **OUTLINE & DIMENSIONS**



### **ENVIRONMENTAL SPECIFICATION**

RoHS Compliance: Storage Temperature Range: Humidity: Hermetic Seal:

Solderability: Reflow: Vibration:

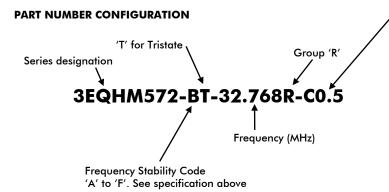
Shock:

RoHS compliant and Pb (lead) free -55° to +125°C 85% RH, 85°C for 48 hours Leak Rate 2x10-8 ATM-cm³/s max. MIL-STD-2002F method 208E 260° for 10 seconds

MIL-STD-202F method 204, 35g 50Hz to 2000Hz

MIL-STD-202F method 213B, test condition: E, 1000g ½ sine wave

### **AVAILABILITY OF SPREAD TYPES AND MODULATION RATES**



SPREAD TYPES and % MODULATION	
DOWN SPREAD	
D1.0	-1%
D3.0	-3%
CENTRE SPREAD	
C0.5	±0.5%
C1.5	±1.5%